



Features

- Surface mount devices
- High voltage surge capabilities
- Available in lead-free version
- Agency Recognition: UL, CSA, TUV

SEL-TISE

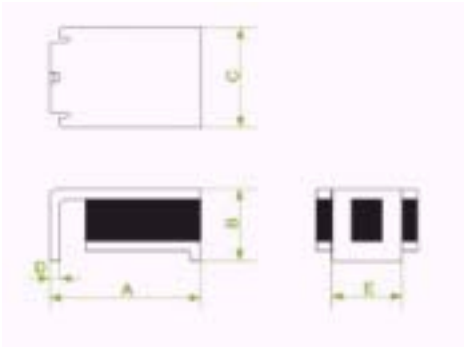


LM series

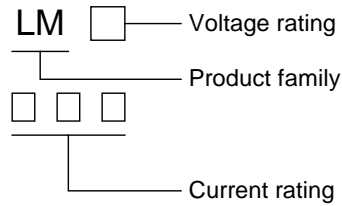
Surface mount devices

Product Dimensions

Part number	A	B	C	D	E
	Max	Max	Max	Min	Typ
LM080	9.4	3.4	7.4	0.3	3.8
LM130	9.4	3.4	7.4	0.3	3.8



Marking system



* Lead-free devices are available, the right logo is lead-free mark of wayon.

Electrical Characteristics

Part number	I _H (A)	I _T (A)	T _{trip} Current(A) Time(S)	V _{max interrupt} (V)	I _{max} (A)	Pd _{typ} (W)	R _{min} ()	R _{max} ()	
LM080	0.080	0.160	1.00	0.45	250	3.0	1.00	14.0	22.0
LM130									

- I_H=Hold current: maximum current at which the device will not trip at 25 °C still air.
- I_T=Trip current: minimum current at which the device will always trip at 25 °C still air.
- V_{max}=Maximum voltage device can withstand without damage at rated current.
- I_{max}=Maximum fault current device can withstand without damage at rated voltage.
- T_{trip}=Maximum time to trip(s) at assigned current.
- Pd_{typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.
- R_{min}=Minimum device resistance at 25 °C prior to tripping.
- R_{max}=Maximum device resistance at 25 °C prior to tripping.

Thermal Derating Chart-I_H(A)

Part number	Maximum ambient operating temperatures()								
	-40	-20	0	25	40	50	60	70	85
LM080	0.124	0.110	0.095	0.080	0.066	0.059	0.051	0.044	0.033
LM130	0.208	0.182	0.156	0.130	0.104	0.091	0.078	0.065	0.045

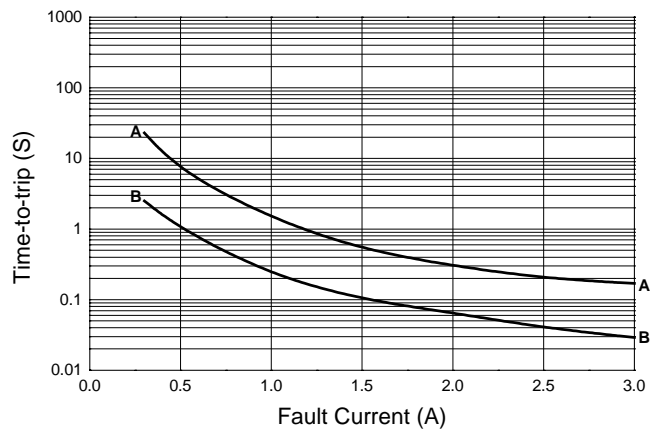
Test Procedures And Requirements

Test	Test Conditions	Accept/Reject Criteria
Resistance	In still air @ 25	R _{min} R R _{max}
Time to Trip	Specified current, V _{max} , 25	T maximum Time to Trip
Hold Current	30min, at I _H	No trip
Trip Cycle Life	V _{max} , I _{max} , 100cycles	No arcing or burning
Trip Endurance	V _{max} , 24hours	No arcing or burning

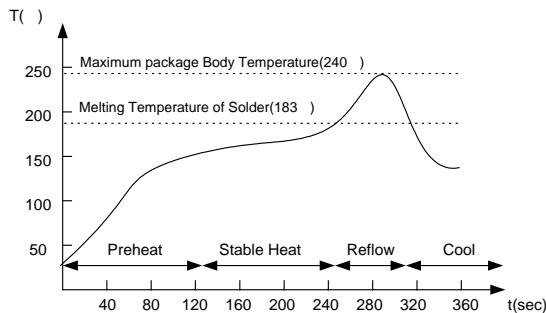
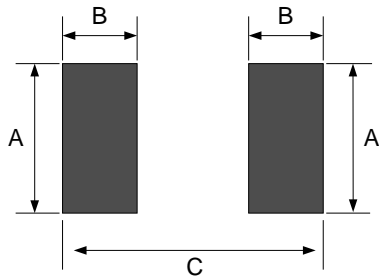
Typical Time-to-Trip Charts at 25

A=LM130

B=LM080



Solder Reflow Recommendations



Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LM080	4.6	1.8	6.1
LM130	4.6	1.8	6.1

* Recommended reflow methods: IR, Vapor phase oven, hot air oven.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Bulk:
LM080~LM130.....1000pcs per bag

Tape & Reel:
LM080~LM130.....1500pcs per reel